

DATE: 12 April, 2023

PCN #: 2619

PCN Title: Qualification of Additional Clip Bonding, Lead Frame Structure

(Matrix) and Mold Compound for Select Automotive Products

# **Dear Customer:**

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



### PRODUCT CHANGE NOTICE

### **PCN-2619 REV1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
12 April, 2023	12 July, 2023	Discrete - Automotive	Clip Bond, Lead Frame, Mold Compound	2619

### TITLE

Qualification of Additional Clip Bonding, Lead Frame Structure (Matrix) and Mold Compound for Select Automotive Products

#### **DESCRIPTION OF CHANGE**

This PCN is being issued to notify customers that in order to assure continuity of supply and to improve assembly manufacturability, Diodes Incorporated has qualified additional clip bonding, lead frame structure (Matrix) and mold compound at Diodes subcontractor Eris Technology Corp. (ERIS) in Taipei, Taiwan for select Automotive products listed below.

Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).

There will be no change to the Fit or Function of affected products.

#### **IMPACT**

No change in datasheet parameters and product performance.

#### **PRODUCTS AFFECTED**

Please refer to Table 1 for the affected automotive products and Figures for comparison of package construction below

#### WFB LINKS

WED ENVIO					
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/				
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/				
Data Sheet:	https://www.diodes.com/catalog/				

## DISCLAIMER

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



Table 1 - Affected Part List							
P6SMAJ12ADFQ-13	P6SMAJ24ADFQ-13	P6SMAJ36ADFQ-13	P6SMAJ64ADFQ-13	S1MDFQ-13	US1DWFQ-7		
P6SMAJ15ADFQ-13	P6SMAJ26ADFQ-13	P6SMAJ43ADFQ-13	P6SMAJ7.5ADFQ-13	S2KDFQ-13	US1JDFQ-13		
P6SMAJ18ADFQ-13	P6SMAJ28ADFQ-13	P6SMAJ5.0ADFQ-13	RS1JDFQ-13	S8MCQ-13	US1MDFQ-13		
P6SMAJ22ADFQ-13	P6SMAJ30ADFQ-13	P6SMAJ6.0ADFQ-13	RS1MDFQ-13	SBR545SAFQ-13	US2JDFQ-13		

Figure 1: Comparison of SMAF (D-FLAT) Package Construction for SKY and GPP products

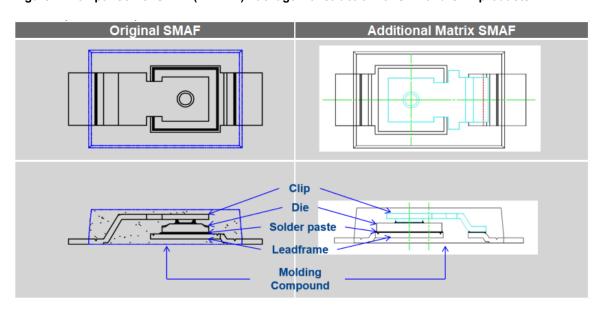


Figure 2: Comparison of SMC Package Construction for GPP product

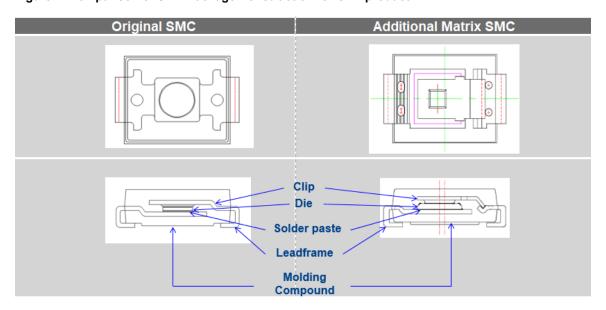




Figure 3: Comparison of SOD-123F Package Construction for GPP product

